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MACRONIX INTERNATIONAL CO., LTD.

MX25L6433F

3V, 64M-BIT [x 1/x 2/x 4]
CMOS MXSMIO® (SERIAL MULTI I/O)
FLASH MEMORY

Key Features

- *Hold Feature*

- *Multi I/O Support - Single I/O, Dual I/O and Quad I/O*

- *Auto Erase and Auto Program Algorithms*

- *Program Suspend/Resume & Erase Suspend/Resume*

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**64M-BIT [x 1 / x 2 / x 4] CMOS MXSMIO® (SERIAL MULTI I/O)
FLASH MEMORY**

1. FEATURES

GENERAL

- Supports Serial Peripheral Interface -- Mode 0 and Mode 3
- 67,108,864 x 1 bit structure
  or 33,554,432 x 2 bits (two I/O read mode) structure
  or 16,777,216 x 4 bits (four I/O mode) structure
- 2048 Equal Sectors with 4K bytes each
  - Any Sector can be erased individually
- 256 Equal Blocks with 32K bytes each
  - Any Block can be erased individually
- 128 Equal Blocks with 64K bytes each
  - Any Block can be erased individually
- Power Supply Operation
  - 2.65~3.6 volt for read, erase, and program operations
- Latch-up protected to 100mA from -1V to Vcc +1V

PERFORMANCE

- High Performance
  VCC = 2.65~3.6V
  - Normal read
    - 50MHz
  - Fast read
    - FAST_READ, DREAD, QREAD:
      133MHz with 8 dummy cycles
    - 2READ: 80MHz with 4 dummy cycles,
                133MHz with 8 dummy cycles
    - 4READ: 80MHz with 6 dummy cycles,
                133MHz with 10 dummy cycles
    - Configurable dummy cycle number for 2READ and 4READ operation
  - 8/16/32/64 byte Wrap-Around Burst Read Mode
- Low Power Consumption
- Typical 100,000 erase/program cycles
- 20 years data retention

SOFTWARE FEATURES

- Input Data Format
  - 1-byte Command code
- Advanced Security Features
  - Block lock protection
    The BP0-BP3 and T/B status bits define the size of the area to be protected against program and erase instructions

- Additional 8K-bit bit security OTP
  - Features unique identifier
  - Factory locked identifiable, and customer lockable
- Auto Erase and Auto Program Algorithms
  - Automatically erases and verifies data at selected sector
  - Automatically programs and verifies data at selected page by an internal algorithm that automatically times the program pulse width (Any page to be programmed should have page in the erased state first.)
- Status Register Feature
- Command Reset
- Program/Erase Suspend
- Program/Erase Resume
- Electronic Identification
  - JEDEC 1-byte Manufacturer ID and 2-byte Device ID
  - RES command for 1-byte Device ID
- Support Serial Flash Discoverable Parameters (SFDP) mode

HARDWARE FEATURES

- SCLK Input
  - Serial clock input
- SI/SIO0
  - Serial Data Input or Serial Data Input/Output for 2 x I/O mode or Serial Data Input/Output for 4 x I/O mode
- SO/SIO1
  - Serial Data Output or Serial Data Input/Output for 2 x I/O mode or Serial Data Input/Output for 4 x I/O mode
- WP#/SIO2
  - Hardware write protection or Serial Data Input/Output for 4 x I/O mode
- HOLD#/SIO3
  - To pause the device without deselecting the device or serial data Input/Output for 4 x I/O mode
- PACKAGE
  - 8-pin SOP (200mil)
  - 16-pin SOP (300mil)
  - 8-WSON (6x5mm)
  - 8-WSON (8x6mm)
  - 24 ball TFBGA (6x8mm)
  - WLCSP
  - **All devices are RoHS Compliant and Halogen-free**

2. GENERAL DESCRIPTION

MX25L6433F is 64Mb bits Serial NOR Flash memory, which is configured as 8,388,608 x 8 internally. When it is in four I/O mode, the structure becomes 16,777,216 bits x 4. When it is in two I/O mode, the structure becomes 33,554,432 bits x 2. MX25L6433F feature a serial peripheral interface and software protocol allowing operation on a simple 3-wire bus while it is in single I/O mode. The three bus signals are a clock input (SCLK), a serial data input (SI), and a serial data output (SO). Serial access to the device is enabled by CS# input.

MX25L6433F, MXSMIO® (Serial Multi I/O) flash memory, provides sequential read operation on the whole chip and multi-I/O features.

When it is in quad I/O mode, the SI pin, SO pin, WP# pin and HOLD# pin become SIO0 pin, SIO1 pin, SIO2 pin and SIO3 pin for address/dummy bits input and data Input/Output.

After program/erase command is issued, auto program/erase algorithms which program/erase and verify the specified page or sector/block locations will be executed. Program command is executed on byte basis, or page (256 bytes) basis. Erase command is executed on 4K-byte sector, 32K-byte/64K-byte block, or whole chip basis.

To provide user with ease of interface, a status register is included to indicate the status of the chip. The status read command can be issued to detect completion status of a program or erase operation via WIP bit.

When the device is not in operation and CS# is high, it is put in standby mode.

The MX25L6433F utilizes Macronix's proprietary memory cell, which reliably stores memory contents even after 100,000 program and erase cycles.

3. PIN CONFIGURATION

8-PIN SOP (200mil)

```
        ┌───────────┐
CS#  □ 1│●          │8 □  VCC
SO/SIO1 □ 2│        │7 □  HOLD#/SIO3
WP#/SIO2 □ 3│       │6 □  SCLK
GND  □ 4│           │5 □  SI/SIO0
        └───────────┘
```

8-WSON (6x5mm, 8x6mm)

```
         ┌────┐
CS#  ■ 1│  ∪  │8 ■  VCC
SO/SIO1 ■ 2│   │7 ■  HOLD#/SIO3
WP#/SIO2 ■ 3│  │6 ■  SCLK
GND  ■ 4│      │5 ■  SI/SIO0
         └─────┘
```

24-Ball TFBGA (6x8 mm)

```
4   ( )    ( )    ( )      ( )       ( )   ( )
    NC     VCC  WP#/SIO2 HOLD#/SIO3  NC    NC

3   ( )    ( )    ( )      ( )       ( )   ( )
    NC     GND    NC     SI/SIO0     NC    NC

2   ( )    ( )    ( )      ( )       ( )   ( )
    NC     SCLK   CS#    SO/SIO1     NC    NC

1   ( )    ( )    ( )      ( )       ( )   ( )
    NC     NC     NC       NC        NC    NC

    A      B      C        D         E     F
```

16-PIN SOP (300mil)

```
           ┌──────────┐
HOLD#/SIO3 □ 1│  ∪     │16 □  SCLK
VCC     □ 2│           │15 □  SI/SIO0
NC      □ 3│           │14 □  NC
NC      □ 4│           │13 □  NC
NC      □ 5│           │12 □  NC
NC      □ 6│           │11 □  NC
CS#     □ 7│           │10 □  GND
SO/SIO1 □ 8│           │9  □  WP#/SIO2
           └──────────┘
```
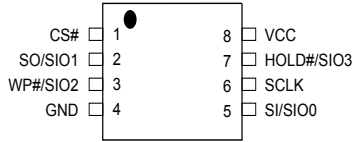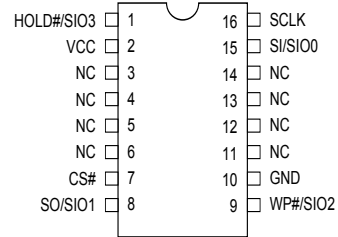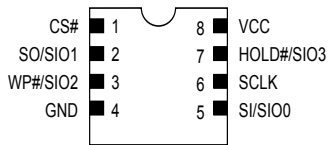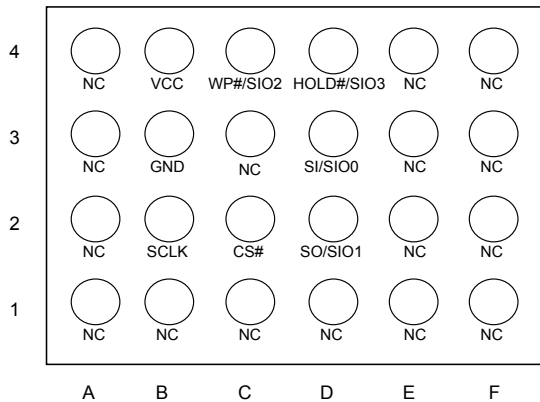
4. PIN DESCRIPTION

SYMBOL	DESCRIPTION
CS#	Chip Select
SI/SIO0	Serial Data Input (for 1xI/O)/ Serial Data Input & Output (for 2xI/O mode and 4xI/O mode)
SO/SIO1	Serial Data Output (for 1xI/O)/Serial Data Input & Output (for 2xI/O mode and 4xI/O mode)
SCLK	Clock Input
WP#/SIO2	Write protection Active Low or Serial Data Input & Output (for 4xI/O mode)
HOLD#/ SIO3	To pause the device without deselecting the device or Serial data Input/Output for 4 x I/O mode
VCC	+ 3.0V Power Supply
GND	Ground
NC	No Connection

Note:
1. The HOLD# pin has internal pull up.

5. BLOCK DIAGRAM

* Depends on part number options.
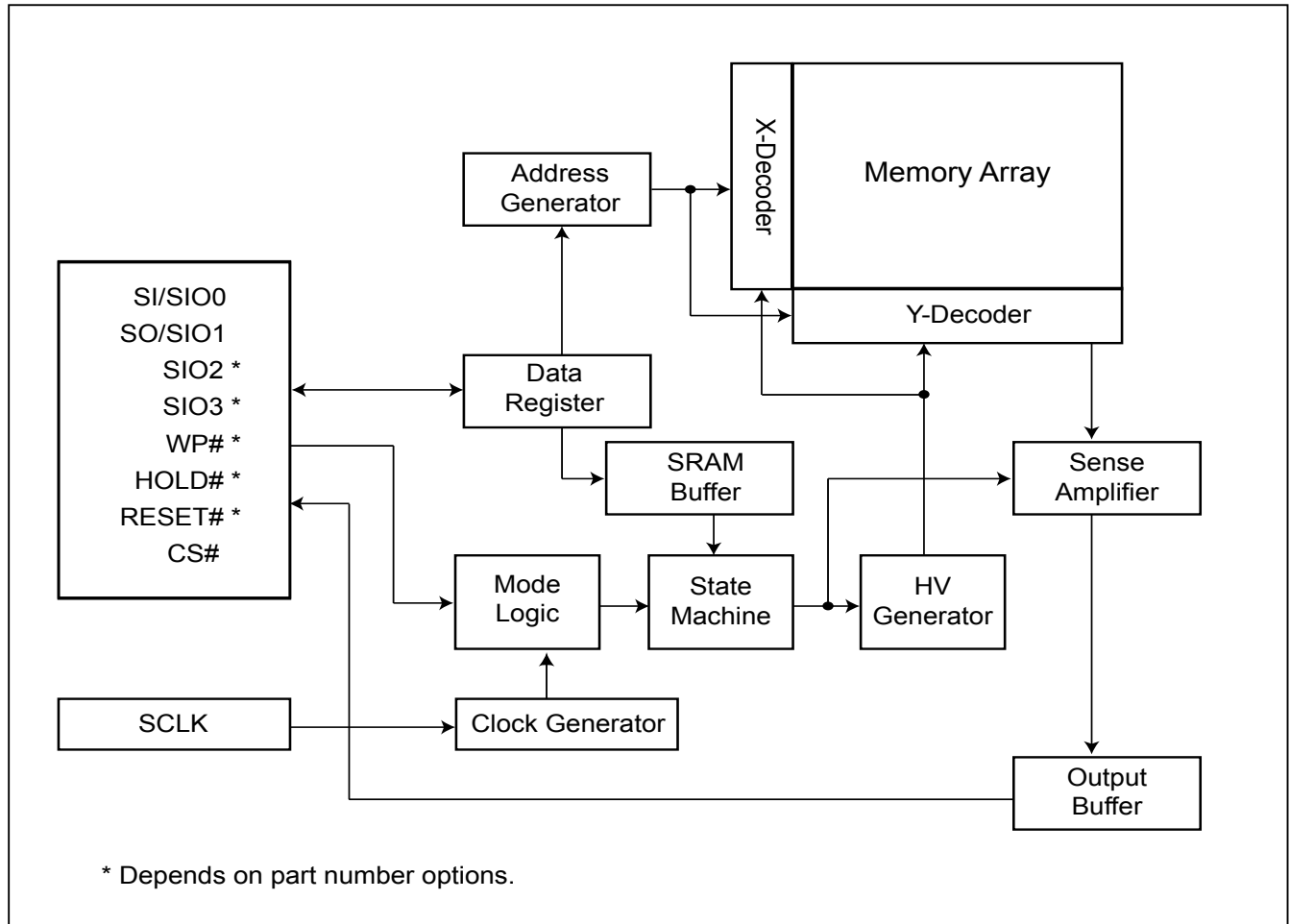
6. DATA PROTECTION

During power transition, there may be some false system level signals which result in inadvertent erasure or programming. The device is designed to protect itself from these accidental write cycles.

The state machine will be reset as standby mode automatically during power up. In addition, the control register architecture of the device constrains that the memory contents can only be changed after specific command sequences have completed successfully.

In the following, there are several features to protect the system from the accidental write cycles during VCC power-up and power-down or from system noise.

• Valid command length checking: The command length will be checked whether it is at byte base and completed on byte boundary.

• Write Enable (WREN) command: WREN command is required to set the Write Enable Latch bit (WEL) before other command to change data.

• Deep Power Down Mode: By entering deep power down mode, the flash device also is under protected from writing all commands except Release from Deep Power Down mode command (RDP) and Read Electronic Signature command (RES).

I. Block lock protection
 - The Software Protected Mode (SPM) uses (TB, BP3, BP2, BP1, BP0) bits to allow part of memory to be protected as read only. The protected area definition is shown as table of *"Table 1. Protected Area Sizes"*, the protected areas are more flexible which may protect various areas by setting value of TB, BP0-BP3 bits.

 - The Hardware Protected Mode (HPM) uses WP#/SIO2 to protect the (BP3, BP2, BP1, BP0, TB) bits and SRWD bit.

Table 1. Protected Area Sizes

Protected Area Sizes (T/B bit = 0)

Status bit				Protect Level
BP3	BP2	BP1	BP0	64Mb
0	0	0	0	0 (none)
0	0	0	1	1 (1block, block 127th)
0	0	1	0	2 (2blocks, block 126th-127th)
0	0	1	1	3 (4blocks, block 124th-127th)
0	1	0	0	4 (8blocks, block 120th-127th)
0	1	0	1	5 (16blocks, block 112th-127th)
0	1	1	0	6 (32blocks, block 96th-127th)
0	1	1	1	7 (64blocks, block 64th-127th)
1	0	0	0	8 (128blocks, protect all)
1	0	0	1	9 (128blocks, protect all)
1	0	1	0	10 (128blocks, protect all)
1	0	1	1	11 (128blocks, protect all)
1	1	0	0	12 (128blocks, protect all)
1	1	0	1	13 (128blocks, protect all)
1	1	1	0	14 (128blocks, protect all)
1	1	1	1	15 (128blocks, protect all)

Protected Area Sizes (T/B bit = 1)

Status bit				Protect Level
BP3	BP2	BP1	BP0	64Mb
0	0	0	0	0 (none)
0	0	0	1	1 (1block, block 0th)
0	0	1	0	2 (2blocks, block 0th-1st)
0	0	1	1	3 (4blocks, block 0th-3rd)
0	1	0	0	4 (8blocks, block 0th-7th)
0	1	0	1	5 (16blocks, block 0th-15th)
0	1	1	0	6 (32blocks, block 0th-31st)
0	1	1	1	7 (64blocks, block 0th-63rd)
1	0	0	0	8 (128blocks, protect all)
1	0	0	1	9 (128blocks, protect all)
1	0	1	0	10 (128blocks, protect all)
1	0	1	1	11 (128blocks, protect all)
1	1	0	0	12 (128blocks, protect all)
1	1	0	1	13 (128blocks, protect all)
1	1	1	0	14 (128blocks, protect all)
1	1	1	1	15 (128blocks, protect all)

Note: The device is ready to accept a Chip Erase instruction if, and only if, all Block Protect (BP3, BP2, BP1, BP0) are 0.

II. Additional 8K-bit secured OTP for unique identifier: to provide 8K-bit One-Time Program area for setting device unique serial number - Which may be set by factory or system maker.

The 8K-bit secured OTP area is composed of two rows of 4K-bit. Customer could lock the first 4K-bit OTP area and factory could lock the other.

- Security register bit 0 indicates whether the 2nd 4K-bit is locked by factory or not.

- Customer may lock-down the customer lockable secured OTP by writing WRSCUR(write security register) command to set customer lock-down bit1 as "1". Please refer to table of *"Table 10. Security Register Definition"* for security register bit definition and table of *"Table 2. 8K-bit Secured OTP Definition"* for address range definition.

- To program 8K-bit secured OTP by entering secured OTP mode (with ENSO command), and going through normal program procedure, and then exiting secured OTP mode by writing EXSO command.

Note: Once lock-down whatever by factory or customer, the corresponding secured area cannot be changed any more. While in 8K-bit Secured OTP mode, array access is not allowed.

Table 2. 8K-bit Secured OTP Definition

Address range	Size	Lock-down
xxx000~xxx1FF	4096-bit	Determined by Customer
xxx200~xxx3FF	4096-bit	Determined by Factory

7. MEMORY ORGANIZATION

Table 3. Memory Organization

Block(64K-byte)	Block(32K-byte)	Sector (4K-byte)	Address Range	
127	255	2047	7FF000h	7FFFFFh
		⋮	⋮	⋮
		2040	7F8000h	7F8FFFh
	254	2039	7F7000h	7F7FFFh
		⋮	⋮	⋮
		2032	7F0000h	7F0FFFh
126	253	2031	7EF000h	7EFFFFh
		⋮	⋮	⋮
		2024	7E8000h	7E8FFFh
	252	2023	7E7000h	7E7FFFh
		⋮	⋮	⋮
		2016	7E0000h	7E0FFFh
125	251	2015	7DF000h	7DFFFFh
		⋮	⋮	⋮
		2008	7D8000h	7D8FFFh
	250	2007	7D7000h	7D7FFFh
		⋮	⋮	⋮
		2000	7D0000h	7D0FFFh

∫

2	5	47	02F000h	02FFFFh
		⋮	⋮	⋮
		40	028000h	028FFFh
	4	39	027000h	027FFFh
		⋮	⋮	⋮
		32	020000h	020FFFh
1	3	31	01F000h	01FFFFh
		⋮	⋮	⋮
		24	018000h	018FFFh
	2	23	017000h	017FFFh
		⋮	⋮	⋮
		16	010000h	010FFFh
0	1	15	00F000h	00FFFFh
		⋮	⋮	⋮
		8	008000h	008FFFh
	0	7	007000h	007FFFh
		⋮	⋮	⋮
		0	000000h	000FFFh

8. DEVICE OPERATION

1. Before a command is issued, status register should be checked to ensure device is ready for the intended operation.

2. When incorrect command is inputted to this device, it enters standby mode and remains in standby mode until next CS# falling edge. In standby mode, SO pin of the device is High-Z.

3. When correct command is inputted to this device, it enters active mode and remains in active mode until next CS# rising edge.

4. For standard single data rate serial mode, input data is latched on the rising edge of Serial Clock(SCLK) and data is shifted out on the falling edge of SCLK. The difference of Serial mode 0 and mode 3 is shown as *"Figure 1. Serial Modes Supported (for Normal Serial mode)"*.

5. For the following instructions: RDID, RDSR, RDSCUR, READ, FAST_READ, RDSFDP, 4READ, QREAD, 2READ, DREAD, RDCR, RES, and REMS the shifted-in instruction sequence is followed by a data-out sequence. After any bit of data being shifted out, the CS# can be high. For the following instructions: WREN, WRDI, WRSR, SE, BE, BE32K, CE, PP, 4PP, Suspend, Resume, NOP, RSTEN, RST, ENSO, EXSO, and WRSCUR, the CS# must go high exactly at the byte boundary; otherwise, the instruction will be rejected and not executed.

6. While a Write Status Register, Program, or Erase operation is in progress, access to the memory array is neglected and will not affect the current operation of Write Status Register, Program, Erase.

Figure 1. Serial Modes Supported (for Normal Serial mode)
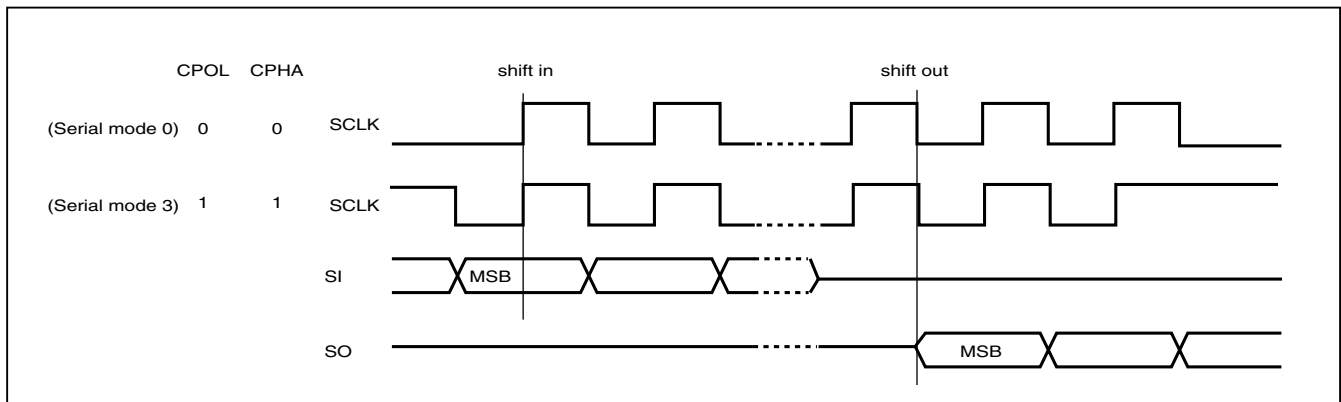
Note:
CPOL indicates clock polarity of Serial master, CPOL=1 for SCLK high while idle, CPOL=0 for SCLK low while not transmitting. CPHA indicates clock phase. The combination of CPOL bit and CPHA bit decides which Serial mode is supported.

9. HOLD FEATURE

HOLD# pin signal goes low to hold any serial communications with the device. The HOLD feature will not stop the operation of write status register, programming, or erasing in progress.

The operation of HOLD requires Chip Select (CS#) keeping low and starts on falling edge of HOLD# pin signal while Serial Clock (SCLK) signal is being low (if Serial Clock signal is not being low, HOLD operation will not start until Serial Clock signal being low). The HOLD condition ends on the rising edge of HOLD# pin signal while Serial Clock(SCLK) signal is being low (if Serial Clock signal is not being low, HOLD operation will not end until Serial Clock being low).

Figure 2. Hold Condition Operation
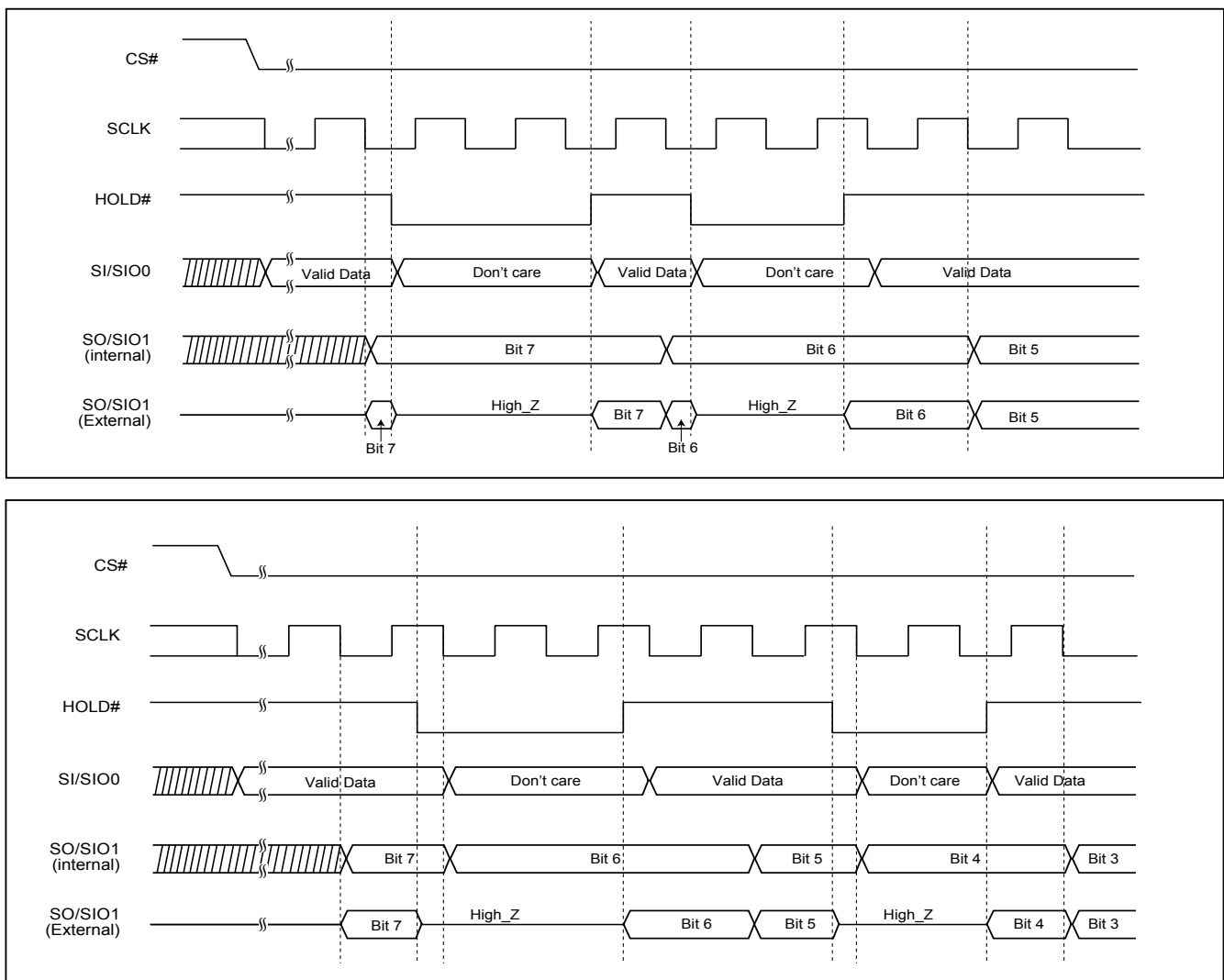
During the HOLD operation, the Serial Data Output (SO) is high impedance when Hold# pin goes low and will keep high impedance until Hold# pin goes high. The Serial Data Input (SI) is don't care if both Serial Clock (SCLK) and Hold# pin goes low and will keep the state until SCLK goes low and Hold# pin goes high. If Chip Select (CS#) drives high during HOLD operation, it will reset the internal logic of the device. To re-start communication with chip, the HOLD# must be at high and CS# must be at low.

Note: The HOLD feature is disabled during Quad I/O mode.

10. COMMAND DESCRIPTION

Table 4. Command Sets

Read Commands

I/O	1	1	2	2	4	4
Command	READ (normal read)	FAST READ (fast read data)	2READ (2 x I/O read command)	DREAD (1I / 2O read command)	4READ (4 x I/O read command)	QREAD (1I/4O read command)
1st byte	03 (hex)	0B (hex)	BB (hex)	3B (hex)	EB (hex)	6B (hex)
2nd byte	ADD1(8)	ADD1(8)	ADD1(4)	ADD1(8)	ADD1(2)	ADD1(8)
3rd byte	ADD2(8)	ADD2(8)	ADD2(4)	ADD2(8)	ADD2(2)	ADD2(8)
4th byte	ADD3(8)	ADD3(8)	ADD3(4)	ADD3(8)	ADD3(2)	ADD3(8)
5th byte		Dummy(8)	Dummy*	Dummy(8)	Dummy*	Dummy(8)
Action	n bytes read out until CS# goes high	n bytes read out until CS# goes high	n bytes read out by 2 x I/O until CS# goes high	n bytes read out by Dual Output until CS# goes high	Quad I/O read with configurable dummy cycles	

Note: *Dummy cycle number will be different, depending on the bit6 (DC) setting of Configuration Register. Please refer to *"Configuration Register"* Table.

Other Commands

Command	WREN (write enable)	WRDI (write disable)	RDSR (read status register)	RDCR (read configuration register)	WRSR (write status/ configuration register)	4PP (quad page program)	SE (sector erase)
1st byte	06 (hex)	04 (hex)	05 (hex)	15 (hex)	01 (hex)	38 (hex)	20 (hex)
2nd byte					Values	ADD1	ADD1
3rd byte					Values	ADD2	ADD2
4th byte						ADD3	ADD3
Action	sets the (WEL) write enable latch bit	resets the (WEL) write enable latch bit	to read out the values of the status register	to read out the values of the configuration register	to write new values of the configuration/ status register	quad input to program the selected page	to erase the selected sector

Command	BE 32K (block erase 32KB)	BE (block erase 64KB)	CE (chip erase)	PP (page program)	DP (Deep power down)	RDP (Release from deep power down)	PGM/ERS Suspend (Suspends Program/ Erase)
1st byte	52 (hex)	D8 (hex)	60 or C7 (hex)	02 (hex)	B9 (hex)	AB (hex)	75/B0 (hex)
2nd byte	ADD1	ADD1		ADD1			
3rd byte	ADD2	ADD2		ADD2			
4th byte	ADD3	ADD3		ADD3			
Action	to erase the selected 32KB block	to erase the selected 64KB block	to erase whole chip	to program the selected page	enters deep power down mode	release from deep power down mode	program/erase operation is interrupted by suspend command

Command	PGM/ERS Resume (Resumes Program/ Erase)	RDID (read identific-ation)	RES (read electronic ID)	REMS (read electronic manufacturer & device ID)	ENSO (enter secured OTP)	EXSO (exit secured OTP)	WRSCUR (write security register)
1st byte	7A/30 (hex)	9F (hex)	AB (hex)	90 (hex)	B1 (hex)	C1 (hex)	2F (hex)
2nd byte			x	x			
3rd byte			x	x			
4th byte			x	ADD			
Action	to continue performing the suspended program/erase sequence	outputs JEDEC ID: 1-byte Manufacturer ID & 2-byte Device ID	to read out 1-byte Device ID	output the Manufacturer ID & Device ID	to enter the 8K-bit secured OTP mode	to exit the 8K-bit secured OTP mode	to set the lockdown bit as "1" (once lockdown, cannot be update)

Command (byte)	RDSCUR (read security register)	RSTEN (Reset Enable)	RST (Reset Memory)	RDSFDP	SBL (Set Burst Length)	NOP (No Operation)
1st byte	2B (hex)	66 (hex)	99 (hex)	5A (hex)	C0/77 (hex)	00 (hex)
2nd byte				ADD1(8)		
3rd byte				ADD2(8)		
4th byte				ADD3(8)		
5th byte				Dummy(8)		
Action	to read value of security register		(Note 2)	Read SFDP mode	to set Burst length	

Note 1: It is not recommended to adopt any other code not in the command definition table, which will potentially enter the hidden mode.

Note 2: The RSTEN command must be executed before executing the RST command. If any other command is issued in-between RSTEN and RST, the RST command will be ignored.

10-1. Write Enable (WREN)

The Write Enable (WREN) instruction is for setting Write Enable Latch (WEL) bit. For those instructions like PP, 4PP, SE, BE, BE32K, CE, and WRSR which are intended to change the device content, should be set every time after the WREN instruction setting the WEL bit.

The sequence of issuing WREN instruction is: CS# goes low→ sending WREN instruction code→ CS# goes high.

The SIO[3:1] are don't care.

Figure 3. Write Enable (WREN) Sequence (Command 06)
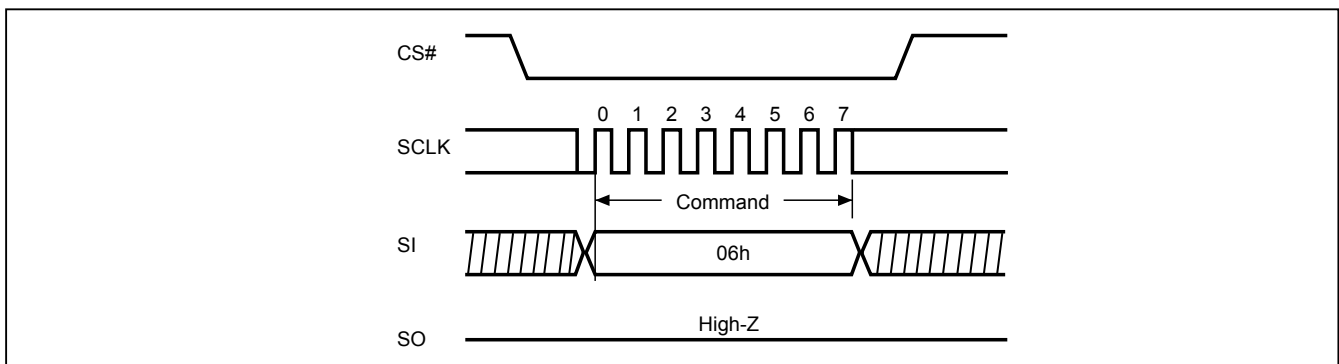
10-2. Write Disable (WRDI)

The Write Disable (WRDI) instruction is for resetting Write Enable Latch (WEL) bit.
The sequence of issuing WRDI instruction is: CS# goes low→ sending WRDI instruction code→ CS# goes high.

The WEL bit is reset by following situations:
  - Power-up
  - WRDI command completion
  - WRSR command completion
  - PP command completion
  - 4PP command completion
  - SE command completion
  - BE32K command completion
  - BE command completion
  - CE command completion
  - PGM/ERS Suspend command completion
  - Soft Reset command completion
  - WRSCUR command completion

Figure 4. Write Disable (WRDI) Sequence (Command 04)
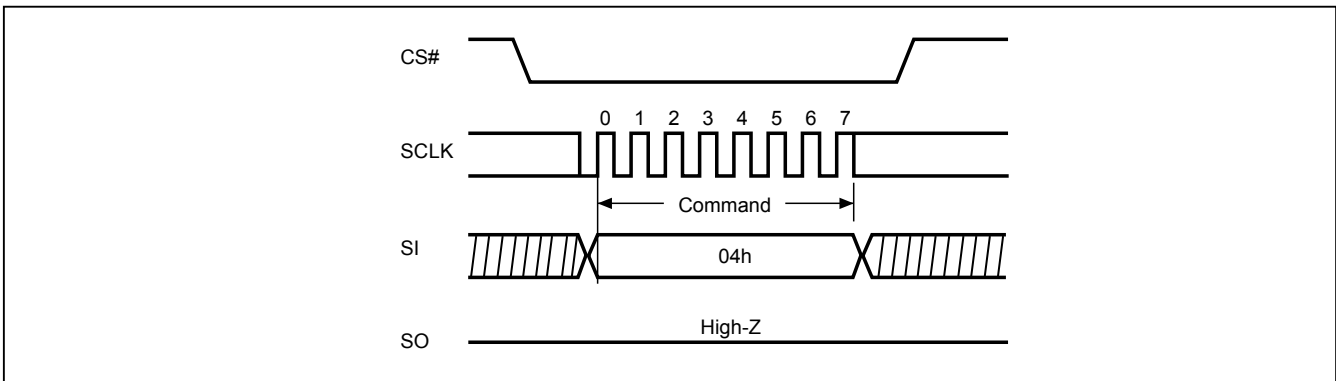
10-3.   Read Identification (RDID)

The RDID instruction is for reading the manufacturer ID of 1-byte and followed by Device ID of 2-byte. The Macronix Manufacturer ID and Device ID are listed as table of *"Table 9. ID Definitions"*.

The sequence of issuing RDID instruction is: CS# goes low→ sending RDID instruction code → 24-bits ID data out on SO→ to end RDID operation can use CS# to high at any time during data out.

While Program/Erase operation is in progress, it will not decode the RDID instruction, so there's no effect on the cycle of program/erase operation which is currently in progress. When CS# goes high, the device is at standby stage.

Figure 5. Read Identification (RDID) Sequence (Command 9F)
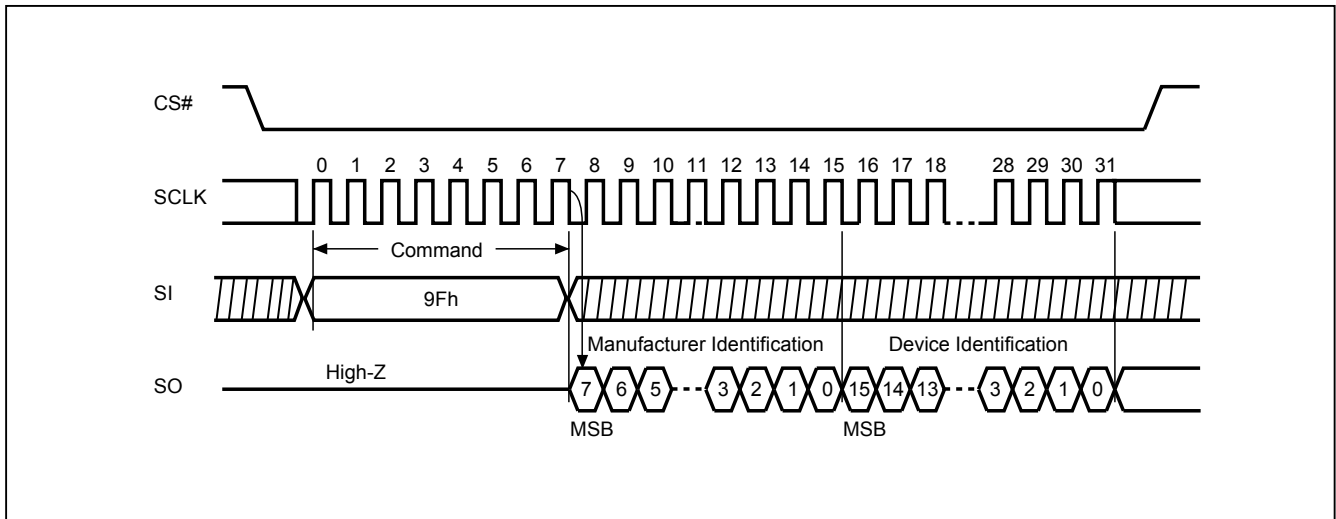
10-4.   Read Status Register (RDSR)

The RDSR instruction is for reading Status Register. The Read Status Register can be read at any time (even in program/erase/write status register condition) and continuously. It is recommended to check the Write in Progress (WIP) bit before sending a new instruction when a program, erase, or write status register operation is in progress.

The sequence of issuing RDSR instruction is: CS# goes low→ sending RDSR instruction code→ Status Register data out on SO.

The SIO[3:1] are don't care.

Figure 6. Read Status Register (RDSR) Sequence (Command 05)
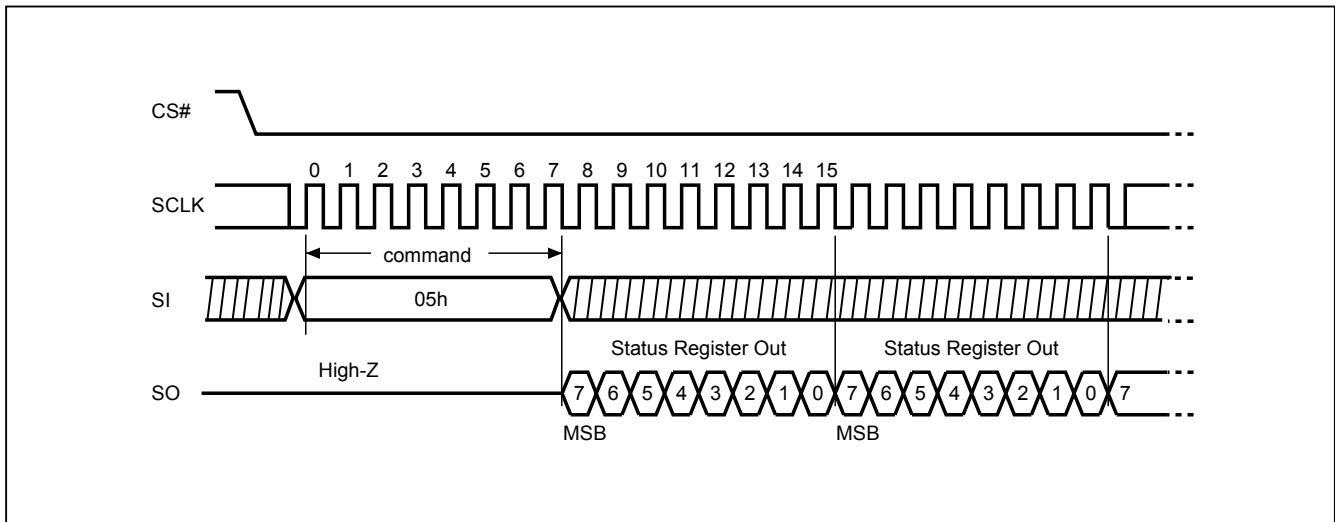
10-5.   Read Configuration Register (RDCR)

The RDCR instruction is for reading Configuration Register Bits. The Read Configuration Register can be read at any time (even in program/erase/write configuration register condition). It is recommended to check the Write in Progress (WIP) bit before sending a new instruction when a program, erase, or write configuration register operation is in progress.

The sequence of issuing RDCR instruction is: CS# goes low→ sending RDCR instruction code→ Configuration Register data out on SO.

The SIO[3:1] are don't care.

Figure 7. Read Configuration Register (RDCR) Sequence
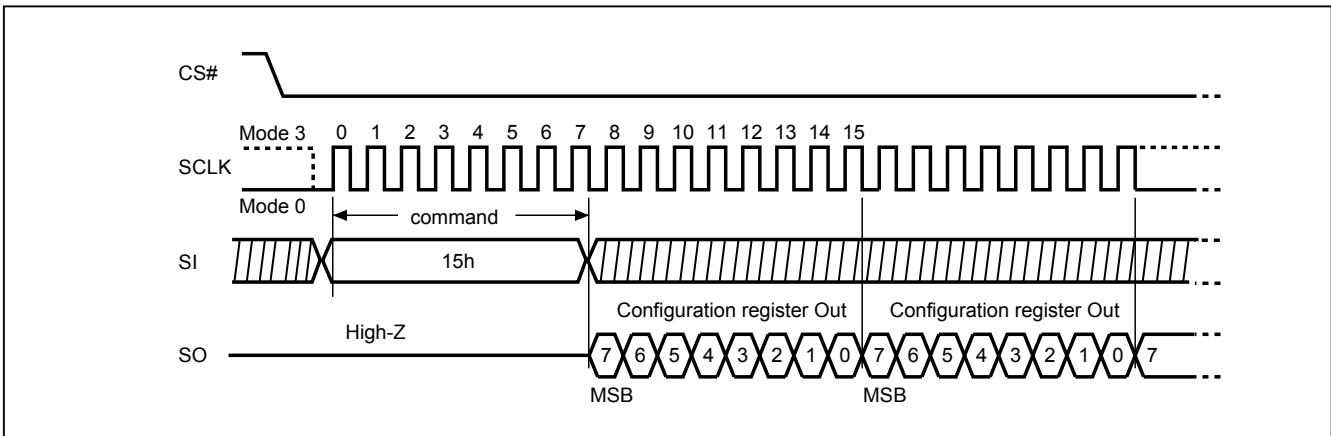
Status Register

The definition of the status register bits is as below:

WIP bit. The Write in Progress (WIP) bit, a volatile bit, indicates whether the device is busy in program/erase/ write status register progress. When WIP bit sets to 1, which means the device is busy in program/erase/write status register progress. When WIP bit sets to 0, which means the device is not in progress of program/erase/ write status register cycle.

WEL bit. The Write Enable Latch (WEL) bit is a volatile bit that is set to "1" by the WREN instruction. WEL needs to be set to "1" before the device can accept program and erase instructions, otherwise the program and erase instructions are ignored. WEL automatically clears to "0" when a program or erase operation completes. To ensure that both WIP and WEL are "0" and the device is ready for the next program or erase operation, it is recommended that WIP be confirmed to be "0" before checking that WEL is also "0". If a program or erase instruction is applied to a protected memory area, the instruction will be ignored and WEL will clear to "0".

BP3, BP2, BP1, BP0 bits. The Block Protect (BP3, BP2, BP1, BP0) bits, non-volatile bits, indicate the protected area (as defined in *"Table 1. Protected Area Sizes"*) of the device to against the program/erase instruction without hardware protection mode being set. To write the Block Protect (BP3, BP2, BP1, BP0) bits requires the Write Status Register (WRSR) instruction to be executed. Those bits define the protected area of the memory to against Page Program (PP), Sector Erase (SE), Block Erase (BE) and Chip Erase (CE) instructions (only if all Block Protect bits set to 0, the CE instruction can be executed). The BP3, BP2, BP1, BP0 bits are "0" as default. Which is un-protected.

QE bit. The Quad Enable (QE) bit is a non-volatile bit with a factory default of "0". When QE is "0", Quad mode commands are ignored; pins WP#/SIO2 and HOLD#/SIO3 function as WP# and HOLD#, respectively. When QE is "1", Quad mode is enabled and Quad mode commands are supported along with Single and Dual mode commands. Pins WP#/SIO2 and HOLD#/SIO3 function as SIO2 and SIO3, respectively, and their alternate pin functions are disabled. Enabling Quad mode also disables the HPM and HOLD features.

SRWD bit. The Status Register Write Disable (SRWD) bit, non-volatile bit, default value is "0". SRWD bit is operated together with Write Protection (WP#/SIO2) pin for providing hardware protection mode. The hardware protection mode requires SRWD sets to 1 and WP#/SIO2 pin signal is low stage. In the hardware protection mode, the Write Status Register (WRSR) instruction is no longer accepted for execution and the SRWD bit and Block Protect bits (BP3, BP2, BP1, BP0) are read only. The SRWD bit defaults to be "0".

Table 5. Status Register

bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0
SRWD (Status Register Write Disable)	QE (Quad Enable)	BP3 (level of protected block)	BP2 (level of protected block)	BP1 (level of protected block)	BP0 (level of protected block)	WEL (write enable latch)	WIP (write in progress bit)
1=status register write disabled 0=status register write enabled	1= Quad Enable 0=not Quad Enable	*(note 1)*	*(note 1)*	*(note 1)*	*(note 1)*	1=write enable 0=not write enable	1=write operation 0=not in write operation
Non-volatile bit	Non-volatile bit	Non-volatile bit	Non-volatile bit	Non-volatile bit	Non-volatile bit	volatile bit	volatile bit

Note 1: Please refer to *"Table 1. Protected Area Sizes"*.

Configuration Register

The Configuration Register is able to change the default status of Flash memory. Flash memory will be configured after the CR bit is set.

ODS bit

The output driver strength ODS bit are volatile bits, which indicate the output driver level of the device. The Output Driver Strength is defaulted=1 when delivered from factory. To write the ODS bit requires the Write Status Register (WRSR) instruction to be executed.

TB bit

The Top/Bottom (TB) bit is a OTP bit. The Top/Bottom (TB) bit is used to configure the Block Protect area by BP bit (BP3, BP2, BP1, BP0), starting from TOP or Bottom of the memory array. The TB bit is defaulted as "0", which means Top area protect. When it is set as "1", the protect area will change to Bottom area of the memory device. To write the TB bit requires the Write Status Register (WRSR) instruction to be executed.

Table 6. Configuration Register

bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0
Reserved	DC (Dummy Cycle)	Reserved	Reserved	TB (top/bottom selected)	Reserved	Reserved	ODS
x	2READ/ 4READ Dummy Cycle	x	x	0=Top area protect 1=Bottom area protect (Default=0)	x	x	0,Output driver strength=1 1,Output driver strength=1/4 (Default=0)
x	volatile	x	x	OTP	x	x	volatile

Note: Please refer to *"Table 7. Dummy Cycle and Frequency Table"*, with "Don't Care" on other Reserved Configuration Registers.

Table 7. Dummy Cycle and Frequency Table

	DC	Numbers of Dummy Cycles	Freq. (MHz)
2READ	0 (default)	4	80 @ 2.65V $\leq$ VCC < 3V
			104 @ VCC $\geq$ 3V
	1	8	133
4READ	0 (default)	6	80 @ 2.65V $\leq$ VCC < 3V
			104 @ VCC $\geq$ 3V
	1	10	133

10-6.   Write Status Register (WRSR)

The WRSR instruction is for changing the values of Status Register Bits and Configuration Register Bits. Before sending WRSR instruction, the Write Enable (WREN) instruction must be decoded and executed to set the Write Enable Latch (WEL) bit in advance. The WRSR instruction can change the value of Block Protect (BP3, BP2, BP1, BP0) bits to define the protected area of memory (as shown in *"Table 1. Protected Area Sizes"*). The WRSR also can set or reset the Quad enable (QE) bit and set or reset the Status Register Write Disable (SRWD) bit in accordance with Write Protection (WP#/SIO2) pin signal, but has no effect on bit1(WEL) and bit0 (WIP) of the status register. The WRSR instruction cannot be executed once the Hardware Protected Mode (HPM) is entered.

The sequence of issuing WRSR instruction is: CS# goes low→ sending WRSR instruction code→ Status Register data on SI→ CS# goes high.

Figure 8. Write Status Register (WRSR) Sequence (Command 01)